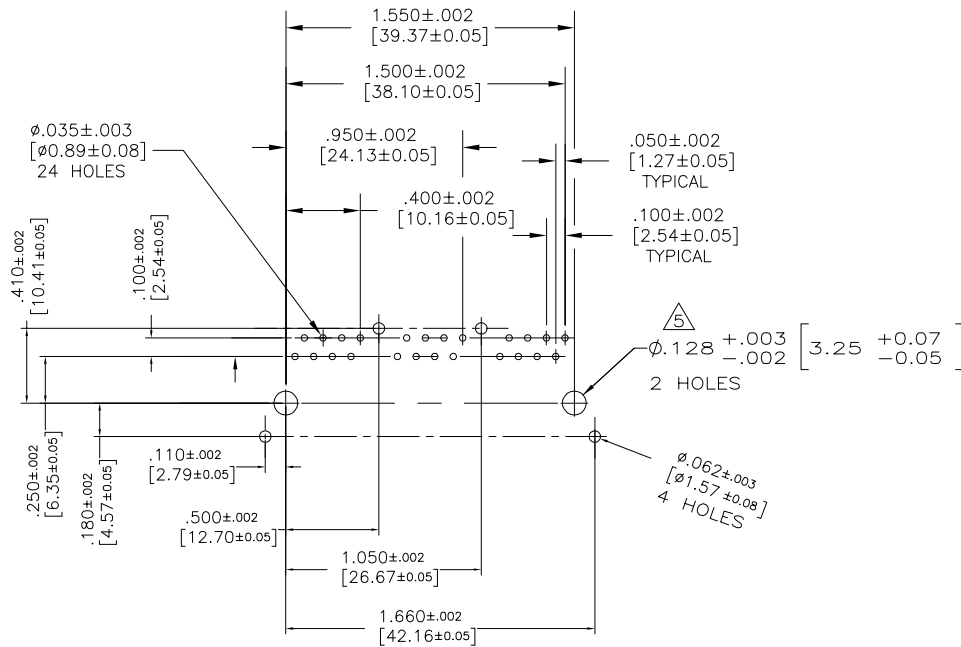
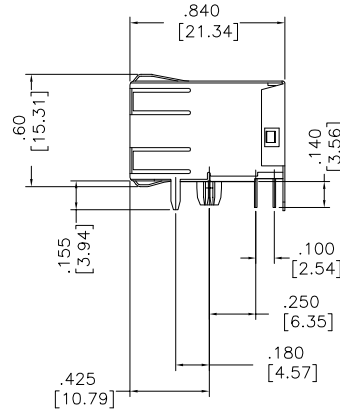
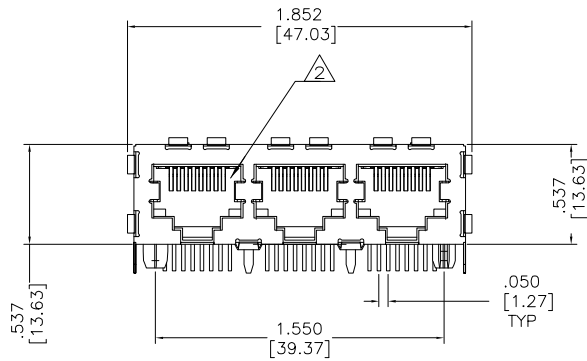


LOC	DIST	REVISIONS					
		P	LTR	DESCRIPTION	DATE	DWN	APVD
AA	00		B1	ECR-09-004284	16APR2009	TY	SY

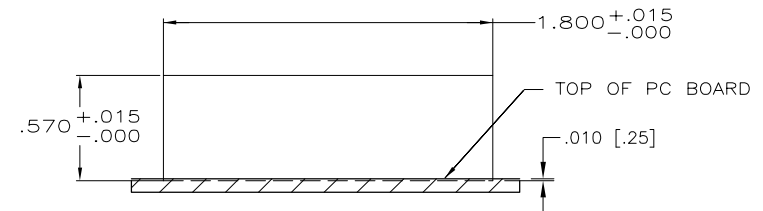


SUGGESTED PC BOARD LAYOUT
COMPONENT SIDE
SEE APPLICATION SPECIFICATION

- MATERIAL: HOUSING - HTN NYLON, BLACK, IR REFLOW PROCESSING COMPATIBLE, UL 94V-0. TERMINALS - .013[0.33] THICK PHOS BRONZE PLATED WITH .000050[1.27µm] THICK HARD GOLD IN LOCALIZED AREA AND .000150[3.81µm] THICK MATTE TIN IN SOLDER AREA OVER .000050[1.27µm] THICK NICKEL UNDERPLATE.

SHIELD - 0.010[.254m] THK. COPPER ALLOY PLATED WITH .000050[1.27µm] MIN. NICKEL AND .000080[2.03µm] MIN. HOT TIN DIP ON PCB GROUND TABS.

- JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS, PART 68 SUBPART F.
- ALL DIMENSIONS SHOWN ARE NOMINAL UNLESS OTHERWISE SPECIFIED.
- ALL DIMENSIONS SHOWN IN BRACKETS [] ARE IN MILLIMETERS.
- USE #30 DRILL BIT OR 3.25 MM DRILL BIT WHEN PRODUCING THESE PRINTED CIRCUIT BOARD HOLES.



SUGGESTED PANEL CUTOUT

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN V. SLACK	1-28-92	Tyco Electronics Corporation Harrisburg, Pa 17105-3608	
DIMENSIONS: INCHES		CHK B. FOX	6-08-92	NAME	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD G. REED	6-08-92	MODULAR JACK ASSEMBLY, THREE PORT, 8 POSITION, RIGHT ANGLE	
0 PLC ± -		PRODUCT SPEC		SIZE	
1 PLC ± -		108-1163		CAGE CODE	
2 PLC ± .01[0.25]		APPLICATION SPEC		DRAWING NO	
3 PLC ± .005[0.13]		114-2048		RESTRICTED TO	
4 PLC ± -		WEIGHT		A2 00779 C=1761825	
ANGLES ± -		CUSTOMER DRAWING		SCALE	
SEE NOTE 1		SEE NOTE 1		2:1	
				SHEET 1 OF 1	
				REV B1	